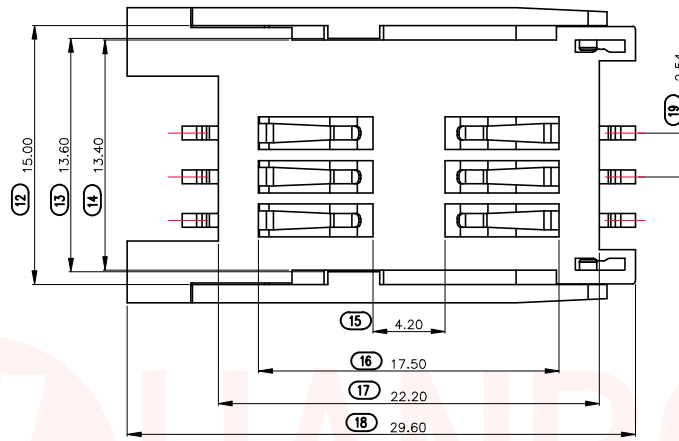
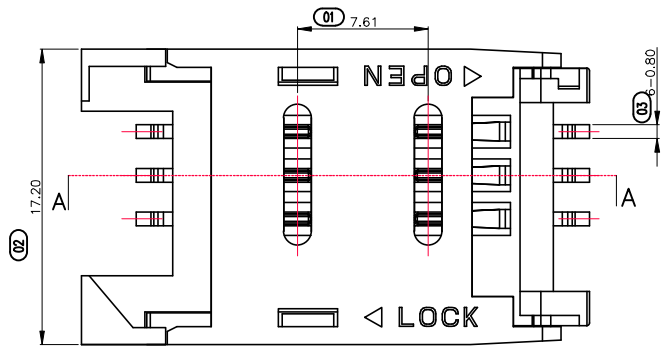


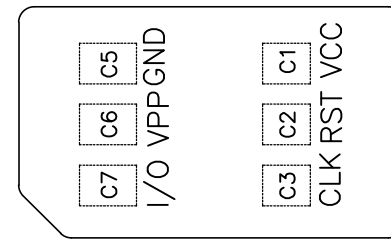
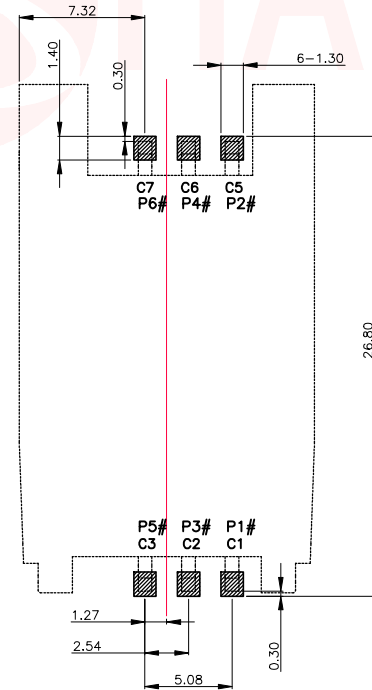
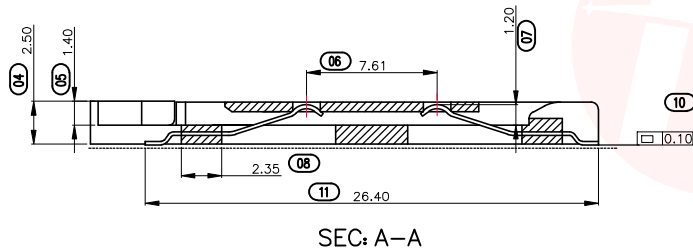


REV.	ECN NO OR DESCRIPTION	REVISED	DATE



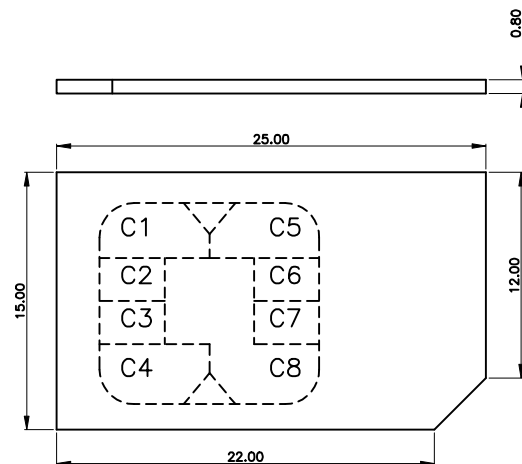
A.Material:
 1.Insulator:High temperature thermoplastic UL94V-0,(BLACK LCP)
 2.Pho.Bronze:Plating,
 50U" MIN NICKEL UNDERPLATED;
 3-8U" GOLD ON THE CONTACT AREA;
 100U" TIN PLATING ON SOLDER TAIL

B.Electrical specifications:
 Voltage rating: 10 V AC
 Current rating: 0.5A
 Dielectric strength: 500V AC for 1 minute min
 Insulation resistance: 1000 M ohm
 Contact resistance: 100 mill.ohm max
 Operation temperature: -25℃ to +95℃
 Product withstanding rff low soldering 260℃ for 10s



SIM 示意图
芯片面朝下视图

PIN NO.	DESCRIPTION
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:I/O
P7#	POL
P8#	DET



RECOMMENDED PCB LAYOUT TOP VIEW (TOLERANCE:±0.05)
 RECOMMENDED MATAL MASK T=0.12MM

UNLESS OTHERWISE SPECIFIED TOLERANCES		东莞市汉博电子科技有限公司 DONGGUAN HANBO TECHNOLOGY CO., LTD			
DECIMALS:	ANGLES:	TITLE	2.5H 6PIN SIM CARD SMT.		
X :±0.30	X :±2°	DWN	xiong	SIM-211-P6	
X.X :±0.20	X.X :±1°	CHKD	lee	SCALE:1:1	UNIT: mm
X.XX :±0.10		APVD	wang	SIZE: A4	SHEET:10F 1
					REV: A4
				CUSTOMER COPY	